



Materials Declaration

Package	QSOP
Body Size/Pitch	150 mils
LeadCount	20
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	6.09 E-03	50678
SiO2 Filler	85	5.18 E-02	430760
Phenol Resin	3	1.83 E-03	15203
Antimony_Sb2O3	1.5	9.14 E-04	7602
Brominated Resin	0.5	3.05 E-04	2534

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.91 E-02	408477
Fe	2.35	1.18 E-03	9845
P	0.03	1.51 E-05	126
Zn	0.12	6.05 E-05	503

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	5.56 E-04	4625

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.69 E-03	22382

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	5.25 E-04	4365

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	4.85 E-03	40293

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.84 E-05	652
Ag Filler	75	2.35 E-04	1956

Package Totals

Weight (g)	PPM
1.20 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information.



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Phenol Resin	3	1.83 E-03	15203
Antimony_Sb2O3	1.5	9.14 E-04	7602
Brominated Resin	0.5	3.05 E-04	2534

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.91 E-02	408477
Fe	2.35	1.18 E-03	9845
P	0.03	1.51 E-05	126
Zn	0.12	6.05 E-05	503

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	5.56 E-04	4625

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.29 E-03	19025
Pb	15	4.04 E-04	3357

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	5.25 E-04	4365

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	4.85 E-03	40293

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.84 E-05	652
Ag Filler	75	2.35 E-04	1956

Package Totals

Weight (g)	PPM
1.20 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
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Die Attach Paste

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